

TRI invites you to visit booths **A1-659** and **B1-538** at **electronica 2016** trade show in Munich on **November 8-11, 2016** for a personal tour of TRI's revolutionary 3D SPI, 3D AOI and ICT testing solutions for Industry 4.0 manufacturing.

TR7500QE World Class 9D AOI

- Complete 2D + 3D Inspection
- IPC-compliant 3D Solder Joint Inspection
- Rapid Programming and New Product Deployment



3D SPI + 3D AOI + CT AXI + ICT
ONE STOP SOLUTION + YMS 4.0 = INDUSTRY 4.0